

SILICONES FOR SEMICONDUCTORS

Solutions for Integrated circuit (IC) packaging and Micro Electro-Mechanical Systems (MEMS)

SILCOOL™ Thermal Interface Materials

Product	Viscosity [Pas @ 20rpm]	T/C [WmK]	Storage modulus (MPa @25C)	Elongation [%]	Adhesion [Mpa]	Feature
SDI 3578	80	3.5	14	60	1.2	Soft adhesive type, low modulus, low stress
SDI 3909	230	3.8	10	100	-	Gel type, low stress, good coverage performance
SDI 5279	130	5.2	20	50	1.5	high thermal conductivity, good dispensability & printability, pass automotive Grade 0
SDI 6089	134	6.0	40	40	1.1	high thermal conductivity, good dispensability
SDI 6889	180	6.8	40	40	1.0	high thermal conductivity, good dispensability
SDI 2089	140	2.0	171	70	4.0	Adhesive type, low BLT, high adhesion performance

Lid Seal

Product	Viscosity [Pas @ 20rpm]	BLT [um]	Hardness [shore A]	Adhesion [Mpa]	Elongation [%]	Curing profile	Features
LA650S	110	N.A.	60	5.5	140	125C @ 90min	Excellent adhesion performance & reliability, pass automotive Grade 0
LA650S-06	110	55	64	5.5	140	125C @ 90min	For around 55um bond line thickness control
LA650S-10	110	100	60	5.5	140	125C @ 90min	For around 100um bond line thickness control
LA650S-15	110	150	60	5.5	140	125C @ 90min	For around 150um bond line thickness control
LA322S	70	N.A.	37	2.5	230	150C @ 60min	Low modulus, low stress